

To all our customers

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Customer Support Dept.  
April 1, 2003

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# HM62W8512B Series

4 M SRAM (512-kword × 8-bit)



ADE-203-904F (Z)  
Rev. 5.0  
Mar. 15, 2000

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## Description

The Hitachi HM62W8512B is a 4-Mbit static RAM organized 512-kword × 8-bit. It realizes higher density, higher performance and low power consumption by employing 0.35 μm Hi-CMOS process technology. The device, packaged in a 525-mil SOP (foot print pitch width) or 400-mil TSOP TYPE II is available for high density mounting. The HM62W8512B is suitable for battery backup system.

## Features

- Single 3.3 V supply: 3.3 V ± 0.3 V
- Access time: 55/70 ns (max)
- Power dissipation
  - Active: 16.5 mW/MHz (typ)
  - Standby: 3.3 μW (typ)
- Completely static memory. No clock or timing strobe required
- Equal access and cycle times
- Common data input and output: Three state output
- Directly LV-TTL compatible: All inputs and outputs
- Battery backup operation

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## HM62W8512B Series

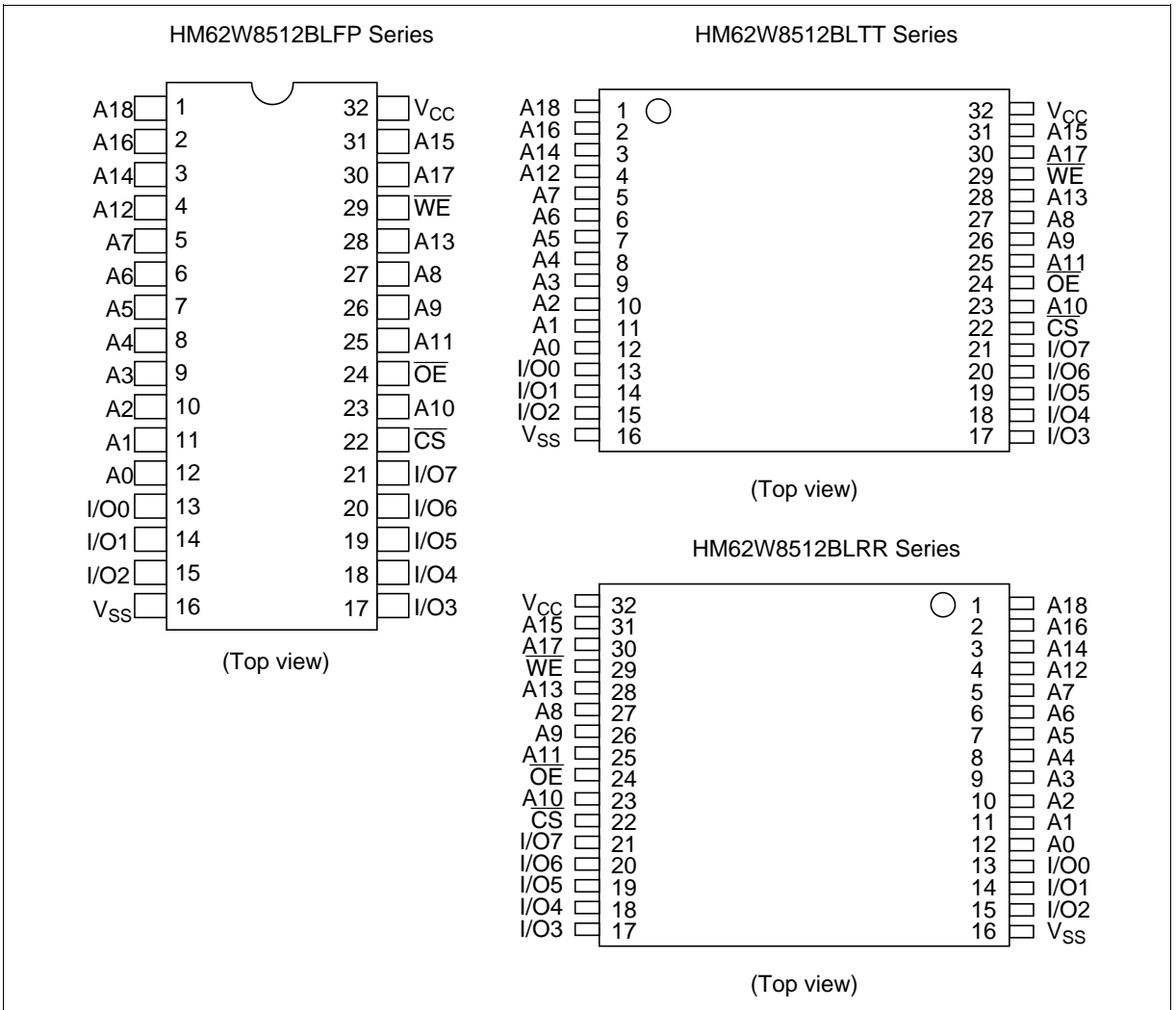
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### Ordering Information

Type No.	Access time	Package
HM62W8512BLFP-5	55 ns	525-mil 32-pin plastic SOP (FP-32D)
HM62W8512BLFP-7	70 ns	
HM62W8512BLFP-5SL	55 ns	
HM62W8512BLFP-7SL	70 ns	
HM62W8512BLFP-5UL	55 ns	
HM62W8512BLFP-7UL	70 ns	
HM62W8512BLTT-5	55 ns	400-mil 32-pin plastic TSOP II (TTP-32D)
HM62W8512BLTT-7	70 ns	
HM62W8512BLTT-5SL	55 ns	
HM62W8512BLTT-7SL	70 ns	
HM62W8512BLTT-5UL	55 ns	
HM62W8512BLTT-7UL	70 ns	
HM62W8512BLRR-5	55 ns	400-mil 32-pin plastic TSOP II reverse (TTP-32DR)
HM62W8512BLRR-7	70 ns	
HM62W8512BLRR-5SL	55 ns	
HM62W8512BLRR-7SL	70 ns	
HM62W8512BLRR-5UL	55 ns	
HM62W8512BLRR-7UL	70 ns	

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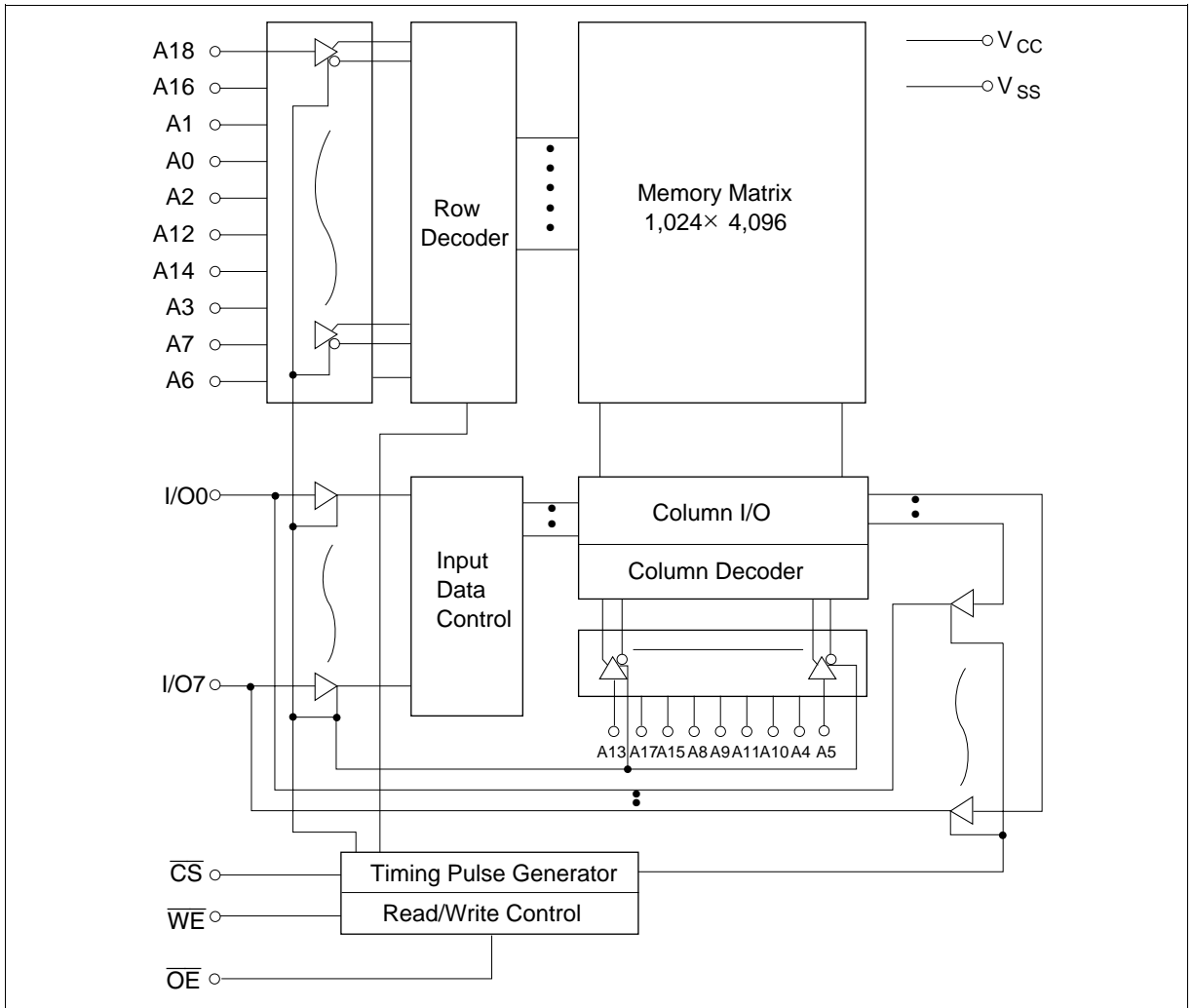
## Pin Arrangement



## Pin Description

Pin name	Function
A0 to A18	Address input
I/O0 to I/O7	Data input/output
CS	Chip select
OE	Output enable
WE	Write enable
V <sub>CC</sub>	Power supply
V <sub>SS</sub>	Ground

## Block Diagram



**Function Table**

$\overline{WE}$	$\overline{CS}$	$\overline{OE}$	Mode	$V_{CC}$ current	Dout pin	Ref. cycle
×	H	×	Not selected	$I_{SB}, I_{SB1}$	High-Z	—
H	L	H	Output disable	$I_{CC}$	High-Z	—
H	L	L	Read	$I_{CC}$	Dout	Read cycle
L	L	H	Write	$I_{CC}$	Din	Write cycle (1)
L	L	L	Write	$I_{CC}$	Din	Write cycle (2)

Note: ×: H or L

**Absolute Maximum Ratings**

Parameter	Symbol	Value	Unit
Power supply voltage	$V_{CC}$	-0.5 to +4.6	V
Voltage on any pin relative to $V_{SS}$	$V_T$	-0.5* <sup>1</sup> to $V_{CC} + 0.5$ * <sup>2</sup>	V
Power dissipation	$P_T$	1.0	W
Operating temperature	$T_{opr}$	-20 to +70	°C
Storage temperature	$T_{stg}$	-55 to +125	°C
Storage temperature under bias	$T_{bias}$	-20 to +85	°C

Notes: 1. -3.0 V for pulse half-width ≤ 30 ns  
 2. Maximum voltage is 4.6 V

**Recommended DC Operating Conditions ( $T_a = -20$  to +70°C)**

Parameter	Symbol	Min	Typ	Max	Unit
Supply voltage	$V_{CC}$	3.0	3.3	3.6	V
	$V_{SS}$	0	0	0	V
Input high voltage	$V_{IH}$	2.0	—	$V_{CC} + 0.3$	V
Input low voltage	$V_{IL}$	-0.3* <sup>1</sup>	—	0.8	V

Note: 1. -3.0 V for pulse half-width ≤ 30 ns

## HM62W8512B Series

**DC Characteristics** ( $T_a = -20$  to  $+70^\circ\text{C}$ ,  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ ,  $V_{SS} = 0\text{ V}$ )

Parameter	Symbol	Min	Typ* <sup>1</sup>	Max	Unit	Test conditions
Input leakage current	$ I_{LI} $	—	—	1	$\mu\text{A}$	$V_{in} = V_{SS}$ to $V_{CC}$
Output leakage current	$ I_{LO} $	—	—	1	$\mu\text{A}$	$\overline{CS} = V_{IH}$ or $\overline{OE} = V_{IH}$ or $\overline{WE} = V_{IL}$ , $V_{IO} = V_{SS}$ to $V_{CC}$
Operating power supply current: DC	$I_{CC}$	—	—	10	$\text{mA}$	$\overline{CS} = V_{IL}$ , others = $V_{IH}/V_{IL}$ , $I_{IO} = 0\text{ mA}$
Operating power supply current	HM62W8512B-5 $I_{CC1}$	—	—	45	$\text{mA}$	Min cycle, duty = 100% $\overline{CS} = V_{IL}$ , others = $V_{IH}/V_{IL}$ $I_{IO} = 0\text{ mA}$
	HM62W8512B-7 $I_{CC1}$	—	—	40	$\text{mA}$	
Operating power supply current	$I_{CC2}$	—	5	10	$\text{mA}$	Cycle time = 1 $\mu\text{s}$ , duty = 100% $I_{IO} = 0\text{ mA}$ , $\overline{CS} \leq 0.2\text{ V}$ $V_{IH} \geq V_{CC} - 0.2\text{ V}$ , $V_{IL} \leq 0.2\text{ V}$
Standby power supply current: DC	$I_{SB}$	—	0.1	0.3	$\text{mA}$	$\overline{CS} = V_{IH}$
Standby power supply current (1): DC	$I_{SB1}$	—	$1^{*2}$	$40^{*2}$	$\mu\text{A}$	$V_{in} \geq 0\text{ V}$ , $\overline{CS} \geq V_{CC} - 0.2\text{ V}$
			$1^{*3}$	$20^{*3}$	$\mu\text{A}$	
			$1^{*4}$	$5^{*4}$	$\mu\text{A}$	
Output low voltage	$V_{OL}$	—	—	0.4	$\text{V}$	$I_{OL} = 2.0\text{ mA}$
				0.2	$\text{V}$	$I_{OL} = 100\ \mu\text{A}$
Output high voltage	$V_{OH}$	$V_{CC} - 0.2$	—	—	$\text{V}$	$I_{OH} = -100\ \mu\text{A}$
		2.4	—	—	$\text{V}$	$I_{OH} = -2.0\text{ mA}$

- Notes: 1. Typical values are at  $V_{CC} = 3.3\text{ V}$ ,  $T_a = +25^\circ\text{C}$  and specified loading, and not guaranteed.  
 2. This characteristics is guaranteed only for L version.  
 3. This characteristics is guaranteed only for L-SL version.  
 4. This characteristics is guaranteed only for L-UL version.

**Capacitance** ( $T_a = +25^\circ\text{C}$ ,  $f = 1\text{ MHz}$ )

Parameter	Symbol	Typ	Max	Unit	Test conditions
Input capacitance* <sup>1</sup>	$C_{in}$	—	8	$\text{pF}$	$V_{in} = 0\text{ V}$
Input/output capacitance* <sup>1</sup>	$C_{IO}$	—	10	$\text{pF}$	$V_{IO} = 0\text{ V}$

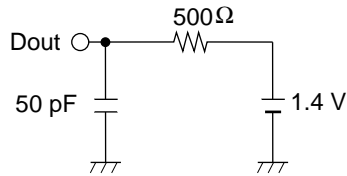
Note: 1. This parameter is sampled and not 100% tested.



**AC Characteristics** ( $T_a = -20$  to  $+70^\circ\text{C}$ ,  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ , unless otherwise noted.)

**Test Conditions**

- Input pulse levels: 0.4 V to 2.4 V
- Input rise and fall time: 5 ns
- Input timing reference levels: 1.4 V
- Output timing reference level: 1.4 V/1.4 V(HM62W8512B-5)  
0.8 V/2.0 V(HM62W8512B-7)
- Output load (Including scope & jig)



**Read Cycle**

HM62W8512B

		-5	-7
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Parameter	Symbol	HM62W8512B				Unit	Notes
		Min	Max	Min	Max		
Read cycle time	$t_{RC}$	55	—	70	—	ns	
Address access time	$t_{AA}$	—	55	—	70	ns	
Chip select access time	$t_{CO}$	—	55	—	70	ns	
Output enable to output valid	$t_{OE}$	—	30	—	35	ns	
Chip selection to output in low-Z	$t_{LZ}$	10	—	10	—	ns	2
Output enable to output in low-Z	$t_{OLZ}$	5	—	5	—	ns	2
Chip deselection to output in high-Z	$t_{HZ}$	0	20	0	30	ns	1, 2
Output disable to output in high-Z	$t_{OHZ}$	0	20	0	30	ns	1, 2
Output hold from address change	$t_{OH}$	10	—	10	—	ns	

## Write Cycle

Parameter	Symbol	HM62W8512B				Unit	Notes
		-5		-7			
		Min	Max	Min	Max		
Write cycle time	$t_{WC}$	55	—	70	—	ns	
Chip selection to end of write	$t_{CW}$	50	—	60	—	ns	4
Address setup time	$t_{AS}$	0	—	0	—	ns	5
Address valid to end of write	$t_{AW}$	50	—	60	—	ns	
Write pulse width	$t_{WP}$	40	—	50	—	ns	3, 12
Write recovery time	$t_{WR}$	0	—	0	—	ns	6
$\overline{WE}$ to output in high-Z	$t_{WHZ}$	0	20	0	30	ns	1, 2, 7
Data to write time overlap	$t_{DW}$	25	—	30	—	ns	
Data hold from write time	$t_{DH}$	0	—	0	—	ns	
Output active from output in high-Z	$t_{OW}$	5	—	5	—	ns	2
Output disable to output in high-Z	$t_{OHZ}$	0	20	0	30	ns	1, 2, 7

Notes: 1.  $t_{HZ}$ ,  $t_{OHZ}$  and  $t_{WHZ}$  are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.

2. This parameter is sampled and not 100% tested.

3. A write occurs during the overlap ( $t_{WP}$ ) of a low  $\overline{CS}$  and a low  $\overline{WE}$ . A write begins at the later transition of  $\overline{CS}$  going low or  $\overline{WE}$  going low. A write ends at the earlier transition of  $\overline{CS}$  going high or  $\overline{WE}$  going high.  $t_{WP}$  is measured from the beginning of write to the end of write.

4.  $t_{CW}$  is measured from  $\overline{CS}$  going low to the end of write.

5.  $t_{AS}$  is measured from the address valid to the beginning of write.

6.  $t_{WR}$  is measured from the earlier of  $\overline{WE}$  or  $\overline{CS}$  going high to the end of write cycle.

7. During this period, I/O pins are in the output state so that the input signals of the opposite phase to the outputs must not be applied.

8. If the  $\overline{CS}$  low transition occurs simultaneously with the  $\overline{WE}$  low transition or after the  $\overline{WE}$  transition, the output remain in a high impedance state.

9. Dout is the same phase of the write data of this write cycle.

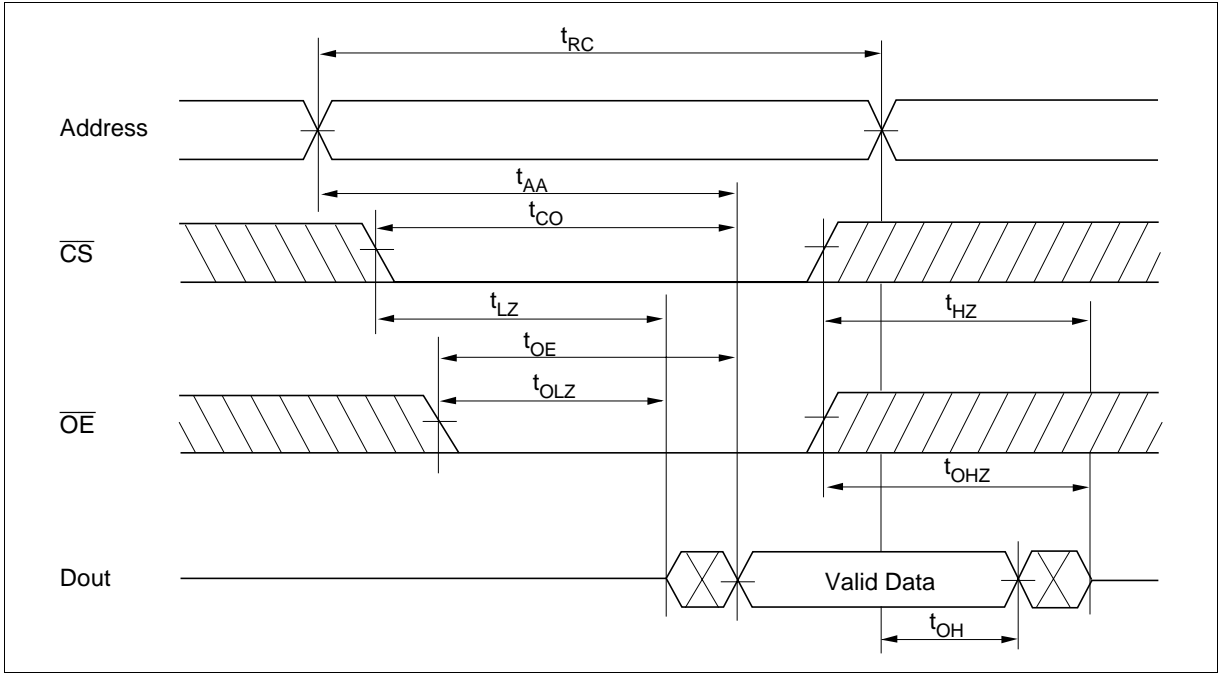
10. Dout is the read data of next address.

11. If  $\overline{CS}$  is low during this period, I/O pins are in the output state. Therefore, the input signals of the opposite phase to the outputs must not be applied to them.

12. In the write cycle with  $\overline{OE}$  low fixed,  $t_{WP}$  must satisfy the following equation to avoid a problem of data bus contention.  $t_{WP} \geq t_{DW} \text{ min} + t_{WHZ} \text{ max}$

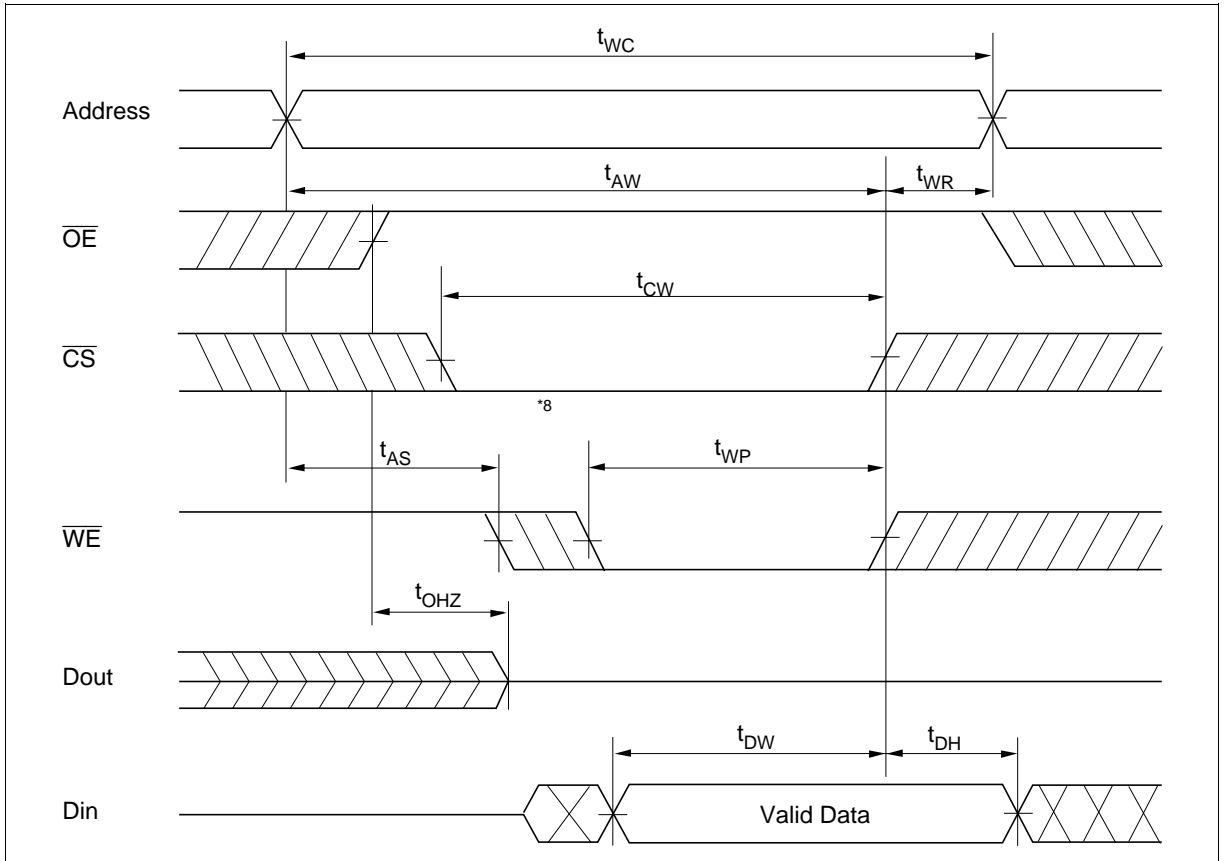
Timing Waveforms

Read Timing Waveform ( $\overline{WE} = V_{IH}$ )

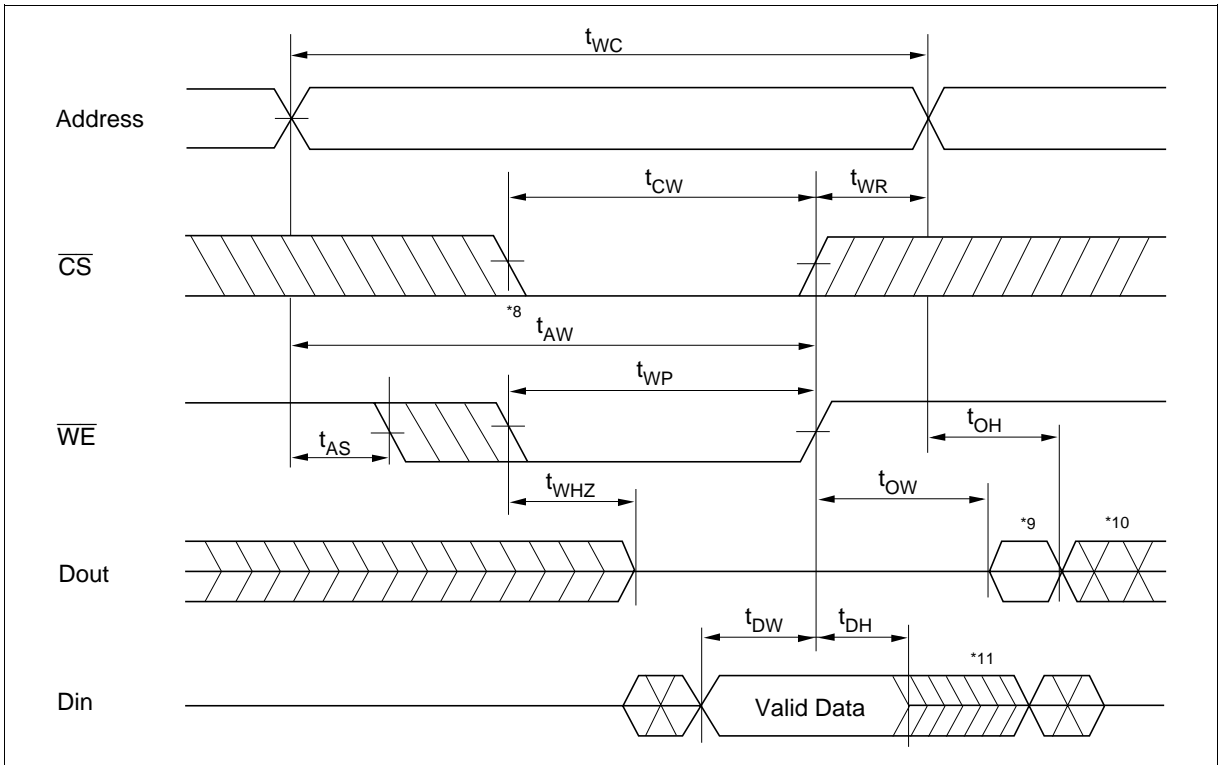


# HM62W8512B Series

## Write Timing Waveform (1) ( $\overline{OE}$ Clock)



Write Timing Waveform (2) ( $\overline{OE}$  Low Fixed)

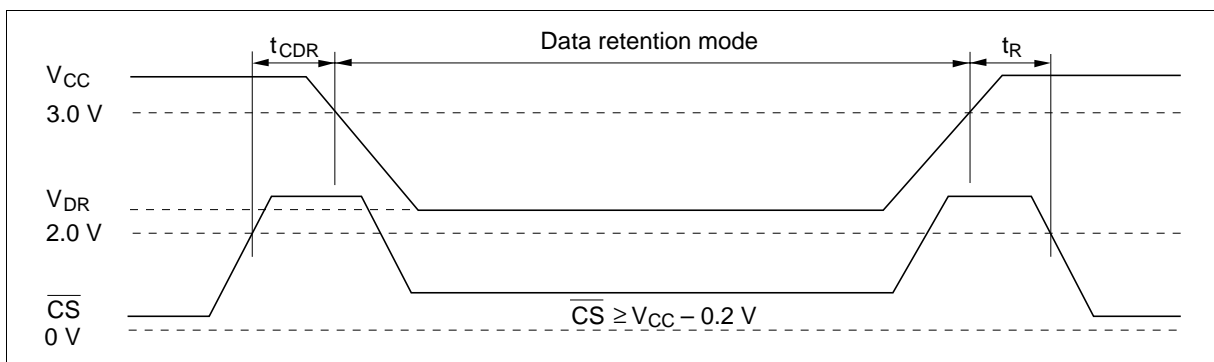


## Low $V_{CC}$ Data Retention Characteristics ( $T_a = -20$ to $+70^\circ\text{C}$ )

Parameter	Symbol	Min	Typ	Max	Unit	Test conditions**4
$V_{CC}$ for data retention	$V_{DR}$	2	—	—	V	$\overline{CS} \geq V_{CC} - 0.2\text{ V}$ , $V_{in} \geq 0\text{ V}$
Data retention current	$I_{CCDR}$	—	$0.8^{*5}$	$20^{*1}$	$\mu\text{A}$	$V_{CC} = 3.0\text{ V}$ , $V_{in} \geq 0\text{ V}$ $\overline{CS} \geq V_{CC} - 0.2\text{ V}$
		—	$0.8^{*5}$	$10^{*2}$	$\mu\text{A}$	
		—	$0.8^{*5}$	$2^{*3}$	$\mu\text{A}$	
Chip deselect to data retention time	$t_{CDR}$	0	—	—	ns	See retention waveform
Operation recovery time	$t_R$	$t_{RC}^{*6}$	—	—	ns	

- Notes:
1. For L-version and  $10\ \mu\text{A}$  (max.) at  $T_a = -20$  to  $+40^\circ\text{C}$ .
  2. For L-SL-version and  $3\ \mu\text{A}$  (max.) at  $T_a = -20$  to  $+40^\circ\text{C}$ .
  3. For L-UL-version and  $2\ \mu\text{A}$  (max.) at  $T_a = -20$  to  $+40^\circ\text{C}$ .
  4.  $\overline{CS}$  controls address buffer,  $\overline{WE}$  buffer,  $\overline{OE}$  buffer, and  $D_{in}$  buffer. In data retention mode,  $V_{in}$  levels (address,  $\overline{WE}$ ,  $\overline{OE}$ , I/O) can be in the high impedance state.
  5. Typical values are at  $V_{CC} = 3.0\text{ V}$ ,  $T_a = +25^\circ\text{C}$  and specified loading, and not guaranteed.
  6.  $t_{RC}$  = read cycle time.

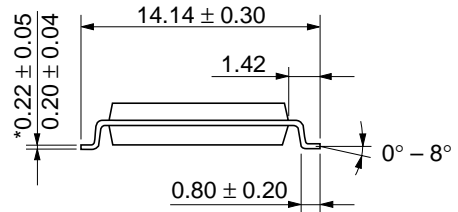
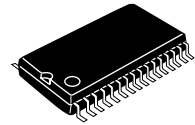
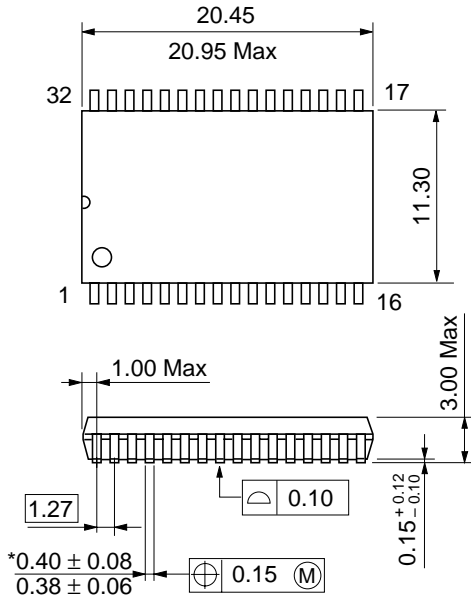
## Low $V_{CC}$ Data Retention Timing Waveform ( $\overline{CS}$ Controlled)



Package Dimensions

HM62W8512BLFP Series (FP-32D)

Unit: mm



\*Dimension including the plating thickness  
Base material dimension

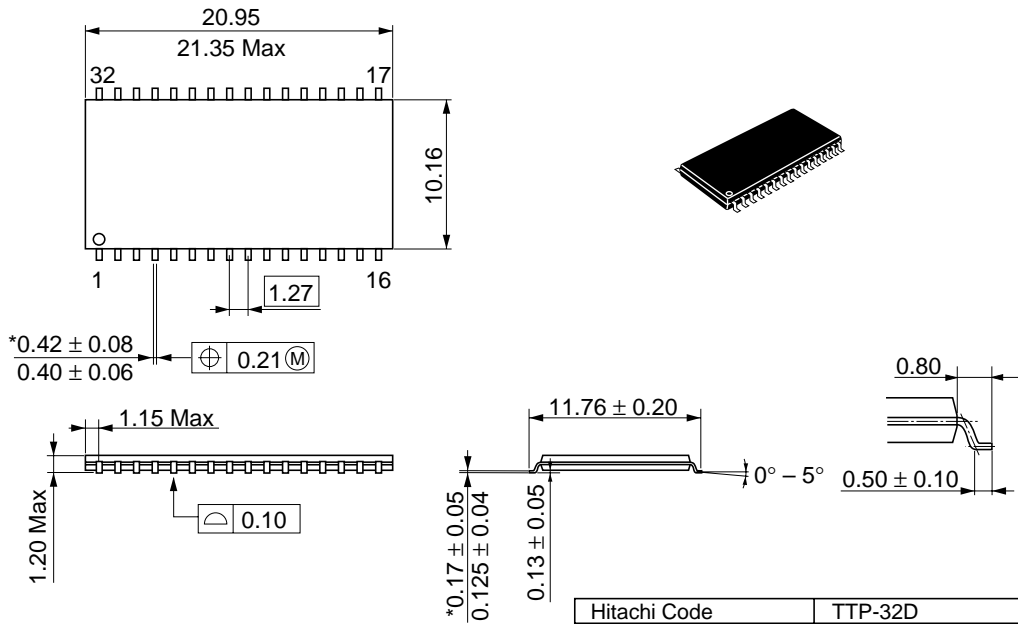
Hitachi Code	FP-32D
JEDEC	Conforms
EIAJ	—
Weight (reference value)	1.3 g

# HM62W8512B Series

## Package Dimensions (cont.)

### HM62W8512BLTT Series (TTP-32D)

Unit: mm



\*Dimension including the plating thickness  
Base material dimension

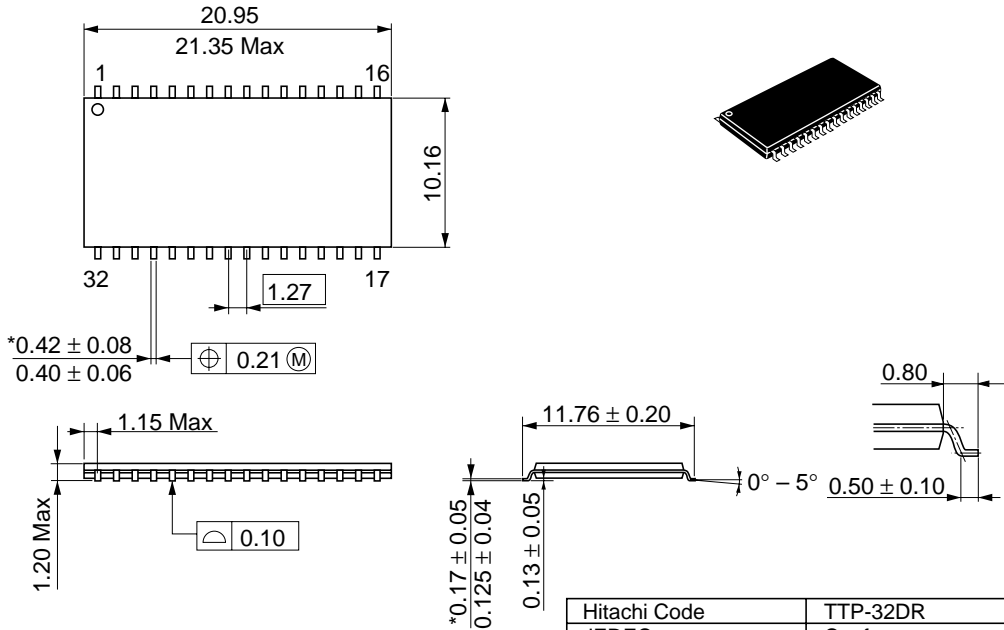
Hitachi Code	TTP-32D
JEDEC	Conforms
EIAJ	—
Weight (reference value)	0.51 g



Package Dimensions (cont.)

HM62W8512BLRR Series (TTP-32DR)

Unit: mm



\*Dimension including the plating thickness  
Base material dimension

Hitachi Code	TTP-32DR
JEDEC	Conforms
EIAJ	—
Weight (reference value)	0.51 g

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